

BCM847BV; BCM847BS; BCM847DS

NPN/NPN matched double transistors

Rev. 06 — 28 August 2009

Product data sheet

1. Product profile

1.1 General description

NPN/NPN matched double transistors in small Surface-Mounted Device (SMD) plastic packages. The transistors are fully isolated internally.

Table 1. Product overview

Type number	Package		PNP/PNP complement	Matched version of
	NXP	JEITA		
BCM847BV	SOT666	-	BCM857BV	BC847BV
BCM847BS	SOT363	SC-88	BCM857BS	BC847BS
BCM847DS	SOT457	SC-74	BCM857DS	-

1.2 Features

- Current gain matching
- Base-emitter voltage matching
- Drop-in replacement for standard double transistors

1.3 Applications

- Current mirror
- Differential amplifier

1.4 Quick reference data

Table 2. Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Per transistor						
V_{CE0}	collector-emitter voltage	open base	-	-	45	V
I_C	collector current		-	-	100	mA
h_{FE}	DC current gain	$V_{CE} = 5\text{ V};$ $I_C = 2\text{ mA}$	200	290	450	

Table 2. Quick reference data ...continued

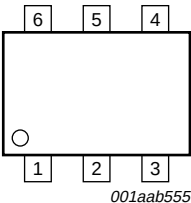
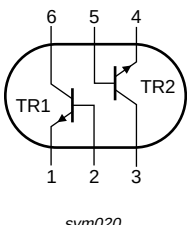
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Per device						
h_{FE1}/h_{FE2}	h_{FE} matching	$V_{CE} = 5\text{ V};$ $I_C = 2\text{ mA}$	[1] 0.9	1	-	
$V_{BE1}-V_{BE2}$	V_{BE} matching	$V_{CE} = 5\text{ V};$ $I_C = 2\text{ mA}$	[2] -	-	2	mV

[1] The smaller of the two values is taken as the numerator.

[2] The smaller of the two values is subtracted from the larger value.

2. Pinning information

Table 3. Pinning

Pin	Description	Simplified outline	Symbol
1	emitter TR1	 001aab555	 sym020
2	base TR1		
3	collector TR2		
4	emitter TR2		
5	base TR2		
6	collector TR1		

3. Ordering information

Table 4. Ordering information

Type number	Package		
	Name	Description	Version
BCM847BV	-	plastic surface-mounted package; 6 leads	SOT666
BCM847BS	SC-88	plastic surface-mounted package; 6 leads	SOT363
BCM847DS	SC-74	plastic surface-mounted package (TSOP6); 6 leads	SOT457

4. Marking

Table 5. Marking codes

Type number	Marking code ^[1]
BCM847BV	3A
BCM847BS	M1*
BCM847DS	R6

[1] * = -: made in Hong Kong

* = p: made in Hong Kong

* = t: made in Malaysia

* = W: made in China

5. Limiting values

Table 6. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
Per transistor					
V_{CBO}	collector-base voltage	open emitter	-	50	V
V_{CEO}	collector-emitter voltage	open base	-	45	V
V_{EBO}	emitter-base voltage	open collector	-	6	V
I_C	collector current		-	100	mA
I_{CM}	peak collector current	single pulse; $t_p \leq 1$ ms	-	200	mA
P_{tot}	total power dissipation	$T_{amb} \leq 25$ °C			
	SOT666		[1][2] -	200	mW
	SOT363		[1] -	200	mW
	SOT457		[1] -	250	mW
Per device					
P_{tot}	total power dissipation	$T_{amb} \leq 25$ °C			
	SOT666		[1][2] -	300	mW
	SOT363		[1] -	300	mW
	SOT457		[1] -	380	mW
T_j	junction temperature		-	150	°C
T_{amb}	ambient temperature		-65	+150	°C
T_{stg}	storage temperature		-65	+150	°C

[1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and standard footprint.

[2] Reflow soldering is the only recommended soldering method.

6. Thermal characteristics

Table 7. Thermal characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Per transistor						
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air				
	SOT666		[1][2] -	-	625	K/W
	SOT363		[1] -	-	625	K/W
	SOT457		[1] -	-	500	K/W

Table 7. Thermal characteristics ...continued

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Per device						
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air				
	SOT666	[1][2]	-	-	416	K/W
	SOT363	[1]	-	-	416	K/W
	SOT457	[1]	-	-	328	K/W

[1] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.

[2] Reflow soldering is the only recommended soldering method.

7. Characteristics

Table 8. Characteristics

$T_{amb} = 25\text{ }^{\circ}\text{C}$ unless otherwise specified

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Per transistor						
I _{CBO}	collector-base cut-off current	V _{CB} = 30 V; I _E = 0 A	-	-	15	nA
		V _{CB} = 30 V; I _E = 0 A; T _j = 150 °C	-	-	5	μA
I _{EBO}	emitter-base cut-off current	V _{EB} = 5 V; I _C = 0 A	-	-	100	nA
h _{FE}	DC current gain	V _{CE} = 5 V; I _C = 10 μA	-	250	-	
		V _{CE} = 5 V; I _C = 2 mA	200	290	450	
V _{CEsat}	collector-emitter saturation voltage	I _C = 10 mA; I _B = 0.5 mA	-	50	200	mV
		I _C = 100 mA; I _B = 5 mA	-	200	400	mV
V _{BEsat}	base-emitter saturation voltage	I _C = 10 mA; I _B = 0.5 mA	[1] -	760	-	mV
		I _C = 100 mA; I _B = 5 mA	[1] -	910	-	mV
V _{BE}	base-emitter voltage	V _{CE} = 5 V; I _C = 2 mA	[2] 610	660	710	mV
		V _{CE} = 5 V; I _C = 10 mA	[2] -	-	770	mV
C _c	collector capacitance	V _{CB} = 10 V; I _E = i _e = 0 A; f = 1 MHz	-	-	1.5	pF
C _e	emitter capacitance	V _{EB} = 0.5 V; I _C = i _c = 0 A; f = 1 MHz	-	11	-	pF

Table 8. Characteristics ...continued $T_{amb} = 25^{\circ}\text{C}$ unless otherwise specified

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
f _T	transition frequency	V _{CE} = 5 V; I _C = 10 mA; f = 100 MHz	100	250	-	MHz
NF	noise figure	V _{CE} = 5 V; I _C = 0.2 mA; R _S = 2 kΩ; f = 10 Hz to 15.7 kHz	-	2.8	-	dB
		V _{CE} = 5 V; I _C = 0.2 mA; R _S = 2 kΩ; f = 1 kHz; B = 200 Hz	-	3.3	-	dB
Per device						
h _{FE1} /h _{FE2}	h _{FE} matching	V _{CE} = 5 V; I _C = 2 mA	[3] 0.9	1	-	
V _{BE1} –V _{BE2}	V _{BE} matching	V _{CE} = 5 V; I _C = 2 mA	[4] -	-	2	mV

[1] V_{BEsat} decreases by about 1.7 mV/K with increasing temperature.[2] V_{BE} decreases by about 2 mV/K with increasing temperature.

[3] The smaller of the two values is taken as the numerator.

[4] The smaller of the two values is subtracted from the larger value.

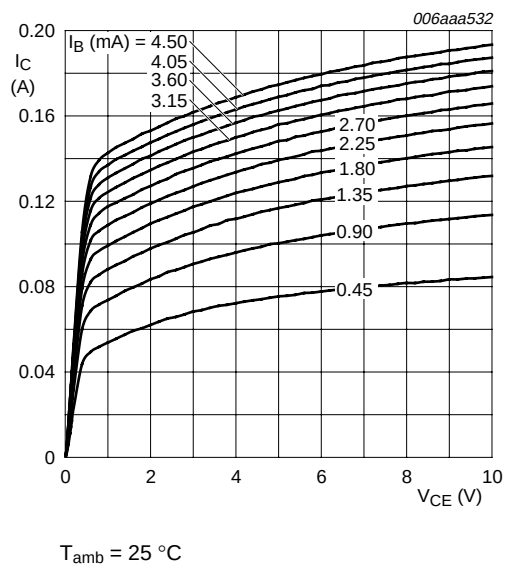


Fig 1. Collector current as a function of collector-emitter voltage; typical values

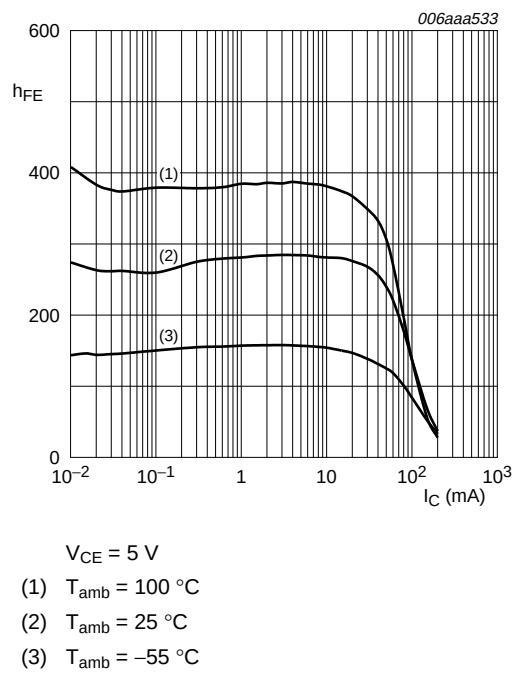


Fig 2. DC current gain as a function of collector current; typical values

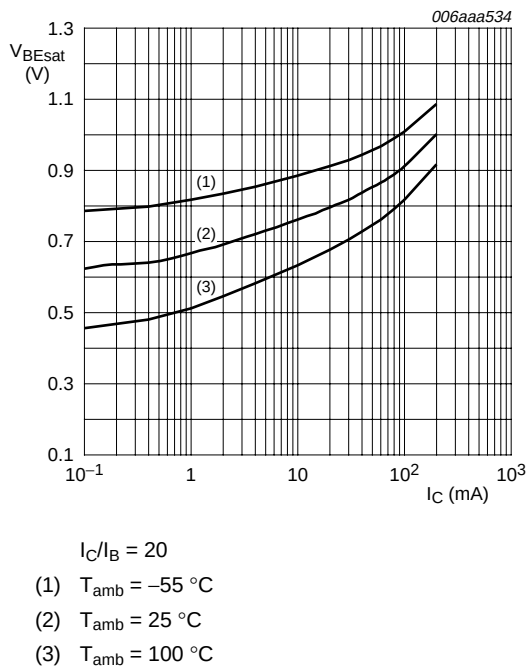


Fig 3. Base-emitter saturation voltage as a function of collector current; typical values

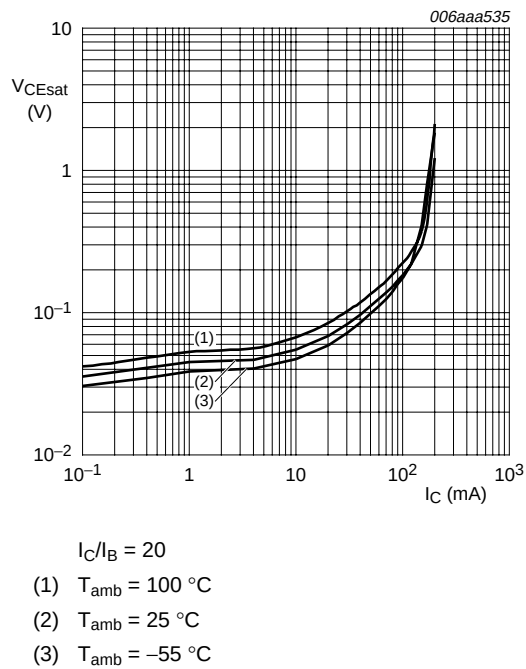


Fig 4. Collector-emitter saturation voltage as a function of collector current; typical values

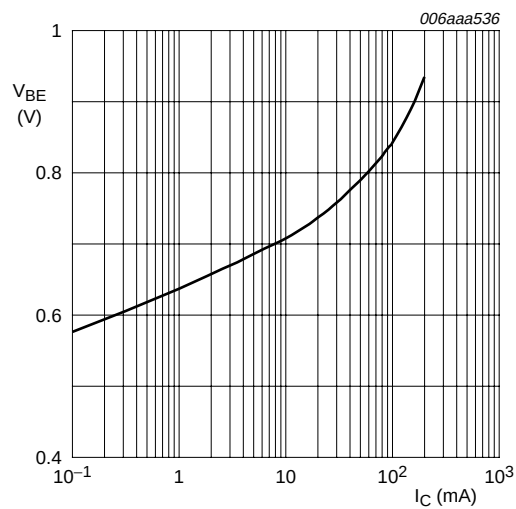


Fig 5. Base-emitter voltage as a function of collector current; typical values

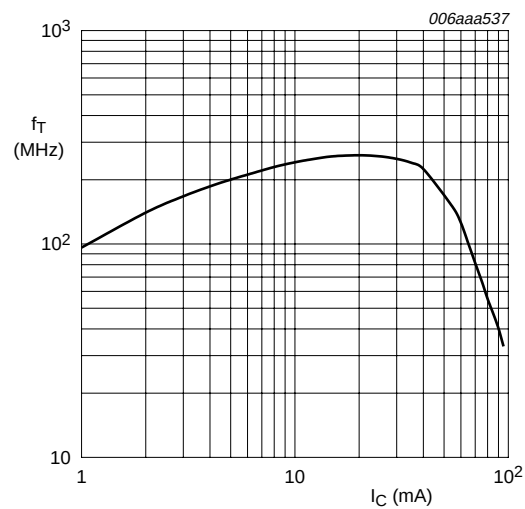


Fig 6. Transition frequency as a function of collector current; typical values

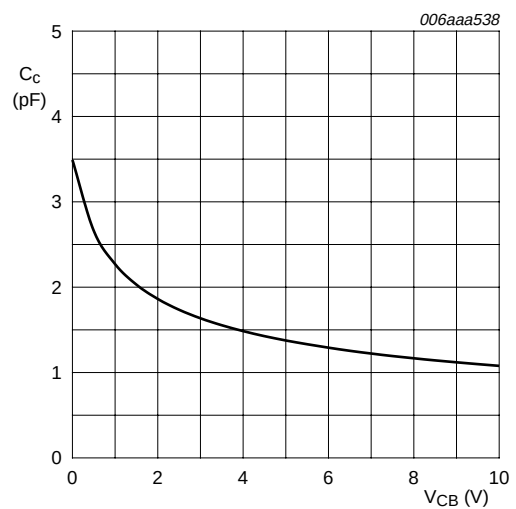


Fig 7. Collector capacitance as a function of collector-base voltage; typical values

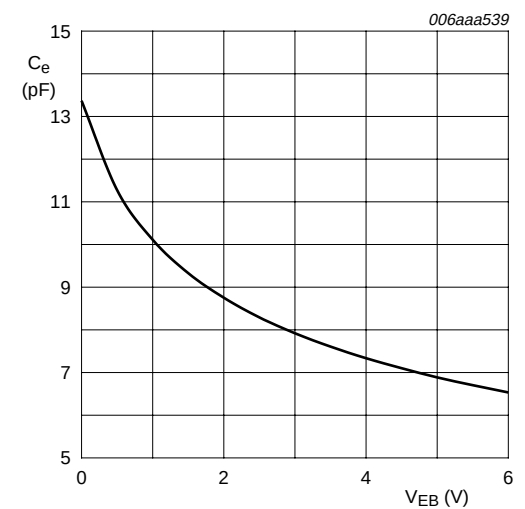
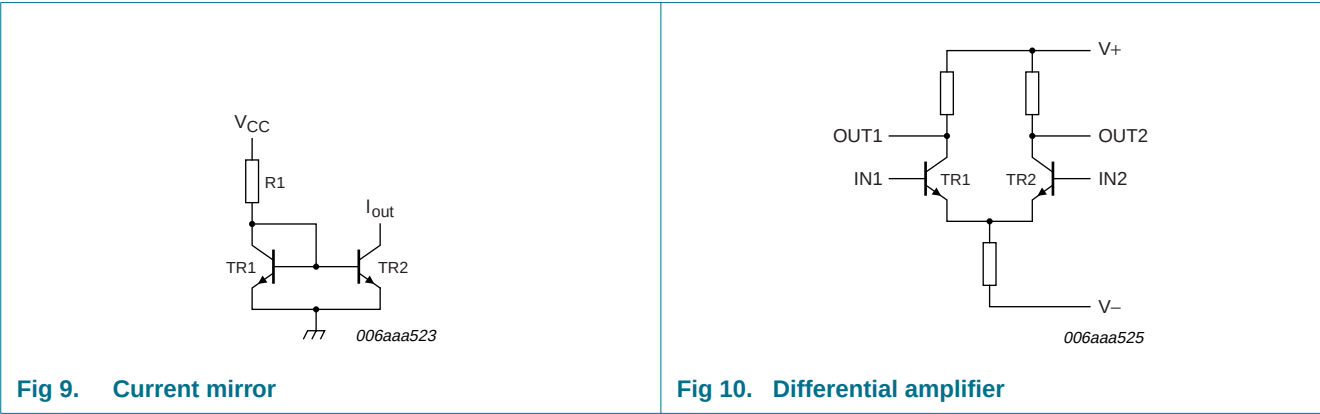
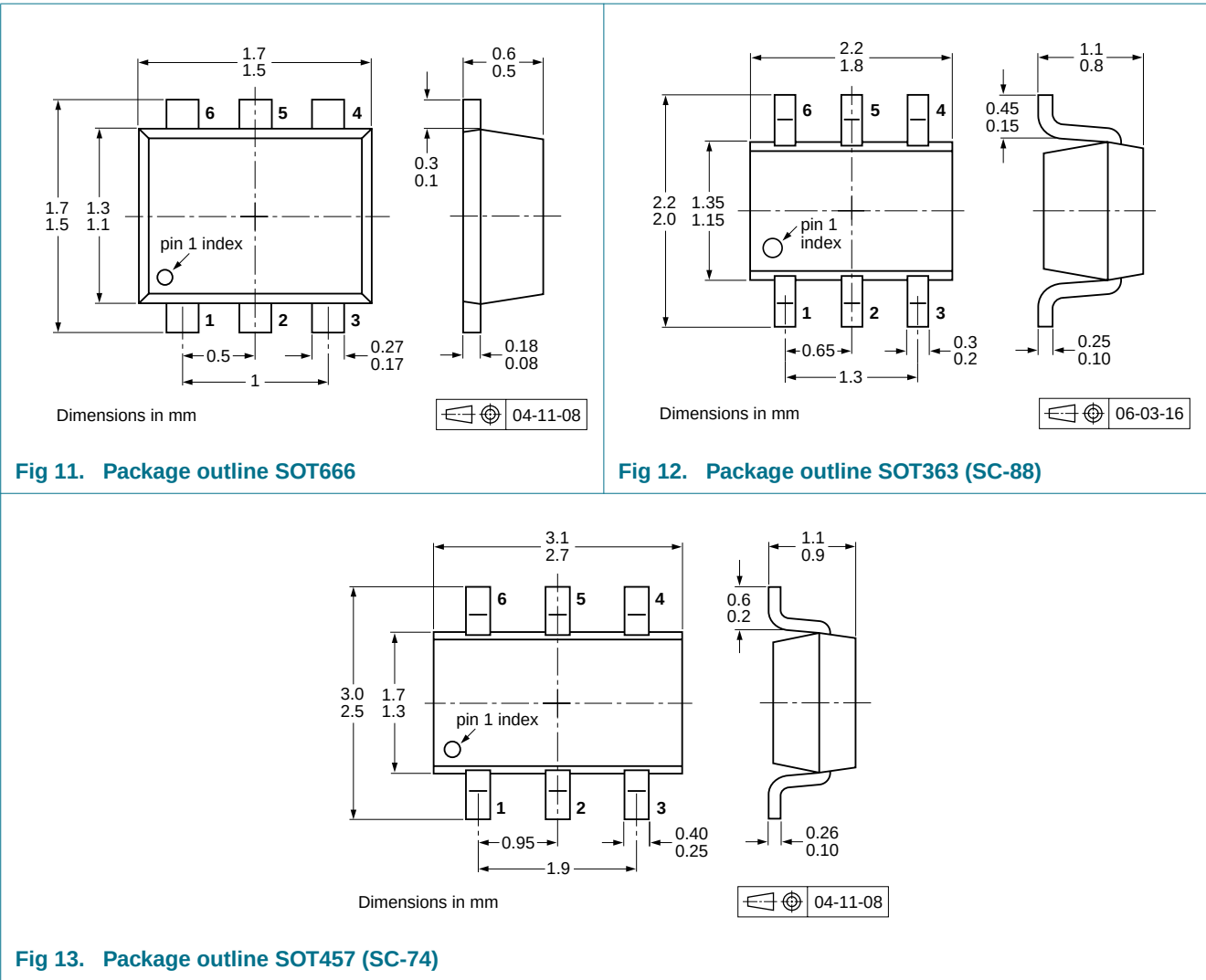


Fig 8. Emitter capacitance as a function of emitter-base voltage; typical values

8. Application information



9. Package outline



10. Packing information

Table 9. Packing methods

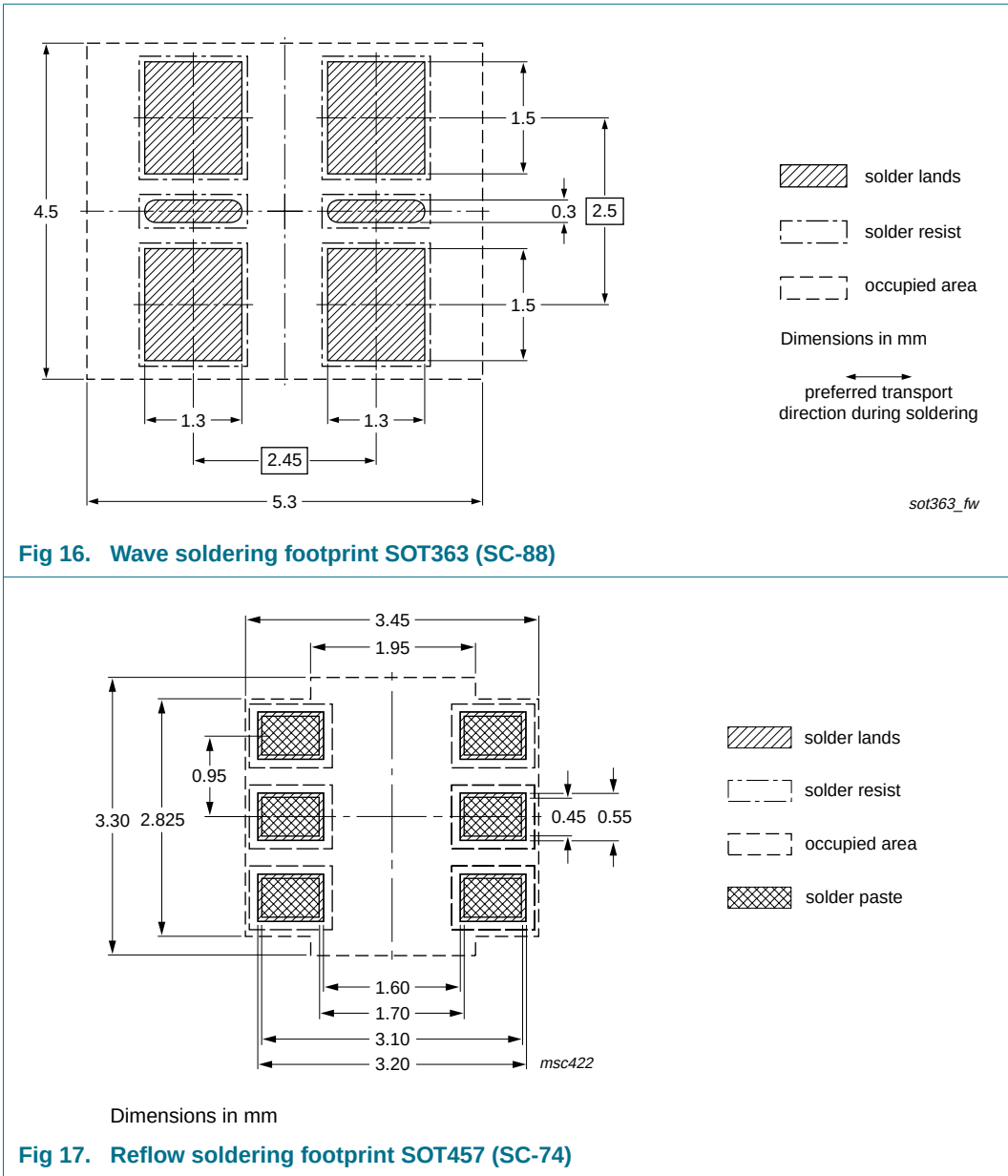
The indicated -xxx are the last three digits of the 12NC ordering code.[\[1\]](#)

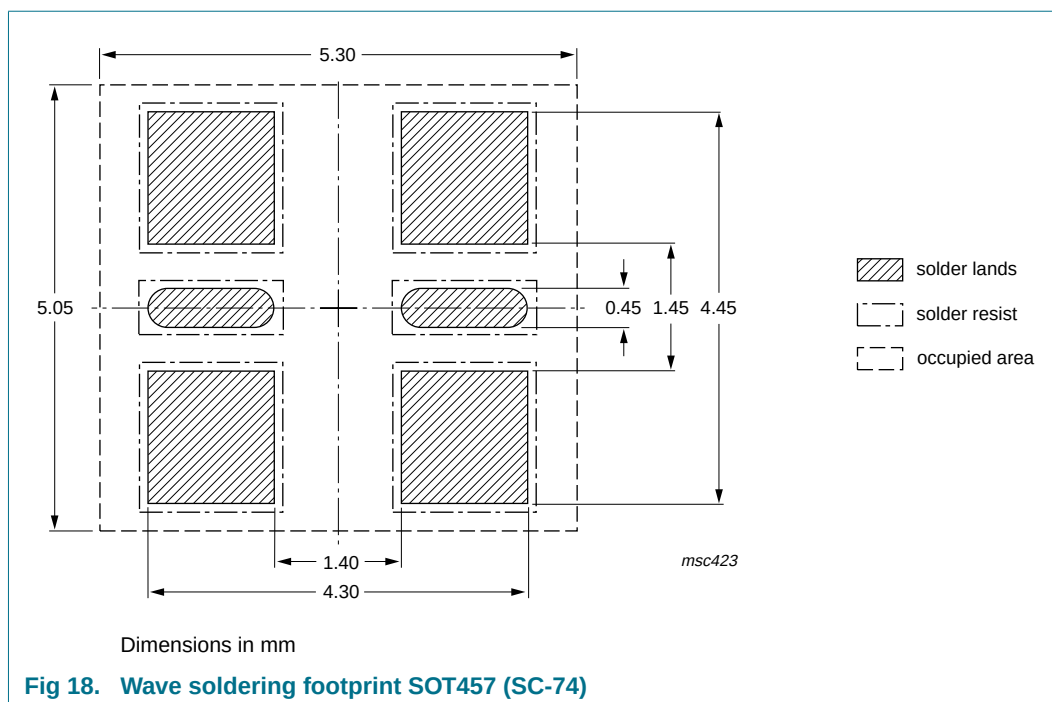
Type number	Package	Description	Packing quantity			
			3000	4000	8000	10000
BCM847BV	SOT666	2 mm pitch, 8 mm tape and reel	-	-	-315	-
		4 mm pitch, 8 mm tape and reel	-	-115	-	-
BCM847BS	SOT363	4 mm pitch, 8 mm tape and reel; T1 [2]	-115	-	-	-135
		4 mm pitch, 8 mm tape and reel; T2 [3]	-125	-	-	-165
BCM847DS	SOT457	4 mm pitch, 8 mm tape and reel; T1 [2]	-115	-	-	-135
		4 mm pitch, 8 mm tape and reel; T2 [3]	-125	-	-	-165

[1] For further information and the availability of packing methods, see [Section 14](#).

[2] T1: normal taping

[3] T2: reverse taping





12. Revision history

Table 10. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
BCM847BV_BS_DS_6	20090828	Product data sheet	-	BCM847BV_BS_DS_5
Modifications: • This data sheet was changed to reflect the new company name NXP Semiconductors, including new legal definitions and disclaimers. No changes were made to the technical content. • Figure 12 "Package outline SOT363 (SC-88)": updated • Figure 14 "Reflow soldering footprint SOT666": updated • Figure 15 "Reflow soldering footprint SOT363 (SC-88)": updated • Figure 16 "Wave soldering footprint SOT363 (SC-88)": updated • Figure 18 "Wave soldering footprint SOT457 (SC-74)": updated				
BCM847BV_BS_DS_5	20060627	Product data sheet	-	BCM847BS_DS_4
BCM847BS_DS_4	20060216	Product data sheet	-	BCM847BS_DS_3
BCM847BS_DS_3	20060123	Product data sheet	-	BCM847BS_2
BCM847BS_2	20050406	Product data sheet	-	BCM847BS_1
BCM847BS_1	20040914	Product data sheet	-	-

13. Legal information

13.1 Data sheet status

Document status ^{[1][2]}	Product status ^[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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